

SSOP4, DC Input, Photo Transistor Couple

Description

The IS281x series combine an AlGaAs infrared emitting diode as the emitter which is optically coupled to a silicon planar phototransistor detector in a plastic SSOP4 package with different lead forming options.

With the robust coplanar double mold structure, IS281x series provide the most stable isolation feature.

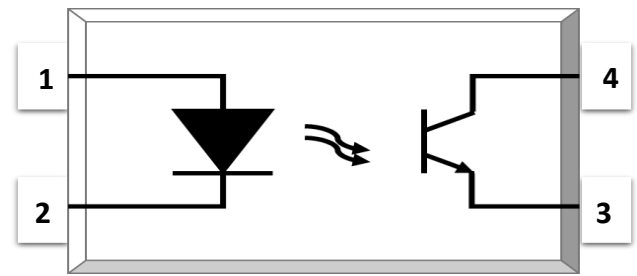
Features

- High isolation 3750 VRMS
- CTR flexibility available see order information
- DC input with transistor output
- Operating temperature range - 55 °C to 110 °C
- REACH compliance
- Halogen free
- MSL class 1

Applications

- Switch mode power supplies
- Programmable controllers
- Household appliances
- Office equipment

SCHEMATIC

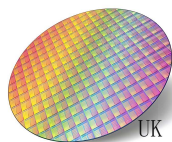


PIN DEFINITION

1. Anode
2. Cathode
3. Emitter
4. Collector

PACKAGE OUTLINE





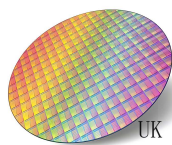
SSOP4, DC Input, Photo Transistor Couple

ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	VALUE	UNIT	NOTE
INPUT				
Forward Current	I_F	60	mA	
Peak Forward Current	I_{FP}	1	A	1
Reverse Voltage	V_R	6	V	
Input Power Dissipation	P_I	100	mW	
OUTPUT				
Collector - Emitter Voltage	V_{CEO}	80	V	
Emitter - Collector Voltage	V_{ECO}	7	V	
Collector Current	I_C	50	mA	
Output Power Dissipation	P_O	150	mW	
COMMON				
Total Power Dissipation	P_{tot}	200	mW	
Isolation Voltage	V_{iso}	3750	V _{rms}	2
Operating Temperature	T_{opr}	-55~110	°C	
Storage Temperature	T_{stg}	-55~125	°C	
Soldering Temperature	T_{sol}	260	°C	

Note 1. 100μs pulse, 100Hz frequency

Note 2. AC For 1 Minute, R.H. = 40 ~ 60%



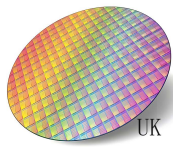
SSOP4, DC Input, Photo Transistor Couple

ELECTRICAL OPTICAL CHARACTERISTICS at Ta=25°C

PARAMETER	SYMBOL	MIN	TYP.	MAX.	UNIT	TEST CONDITION	NOTE
INPUT							
Forward Voltage	V_F	-	-	1.4	V	$I_F=10\text{mA}$	
Reverse Current	I_R	-	-	10	μA	$V_R=6\text{V}$	
Input Capacitance	C_{in}	-	10	-	pF	$V=0, f=1\text{kHz}$	
OUTPUT							
Collector Dark Current	I_{CEO}	-	-	100	nA	$V_{CE}=20\text{V}, I_F=0$	
Collector-Emitter Breakdown Voltage	BV_{CEO}	80	-	-	V	$I_C=0.1\text{mA}, I_F=0$	
Emitter-Collector Breakdown Voltage	BV_{ECO}	7	-	-	V	$I_E=0.1\text{mA}, I_F=0$	
TRANSFER CHARACTERISTICS							
Current Transfer Ratio	281	CTR	50	-	600	$I_F=5\text{mA}, V_{CE}=5\text{V}$	
	281GB		100	-	600		
	281GR		100	-	300		
	281GRL		100	-	200		
	281GRH		150	-	300		
Collector-Emitter Saturation Voltage	$V_{CE(sat)}$	-	0.1	0.2	V	$I_F=10\text{mA}, I_C=1\text{mA}$	
Isolation Resistance	R_{ISO}	10^{12}	10^{14}	-	Ω	DC500V, 40 ~ 60% R.H.	
Floating Capacitance	C_{IO}	-	0.4	1	pF	$V=0, f=1\text{MHz}$	
Response Time (Rise)	t_r	-	3	18	μs	$V_{CE}=2\text{V}, I_C=2\text{mA}$ $R_L=100\Omega$	3
Response Time (Fall)	t_f	-	4	18	μs		3
Cut-off Frequency	f_c	-	80	-	kHz	$V_{CE}=2\text{V}, I_C=2\text{mA}$ $R_L=100\Omega, -3\text{dB}$	4

Note 3. Fig.12&13

Note 4. Fig.14



CHARACTERISTIC CURVES

Fig.1 Forward Current vs. Ambient Temperature

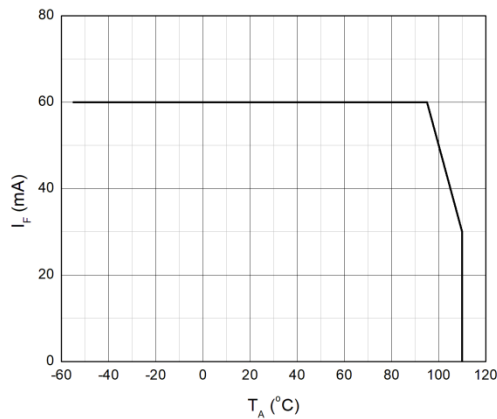


Fig.2 Collector Power Dissipation vs. Ambient Temperature

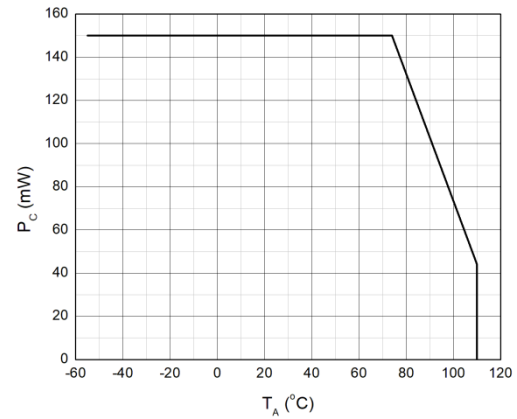


Fig.3 Forward Current vs. Forward Voltage

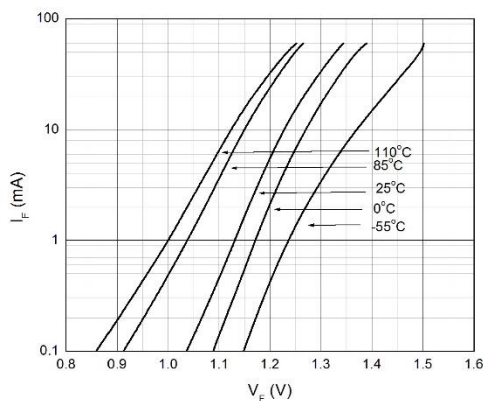


Fig.4 Collector Dark Current vs. Ambient Temperature

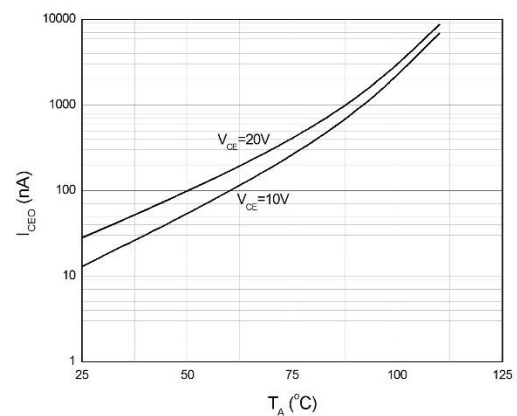


Fig.5 Collector Current vs. Collector-emitter Voltage

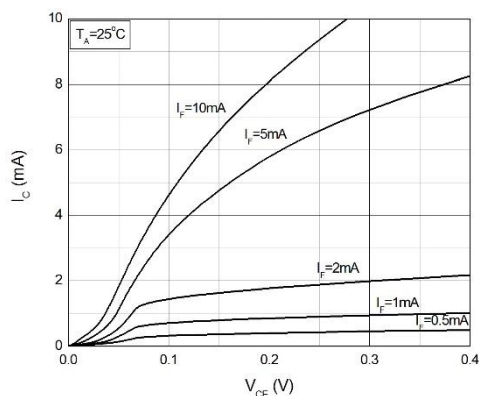
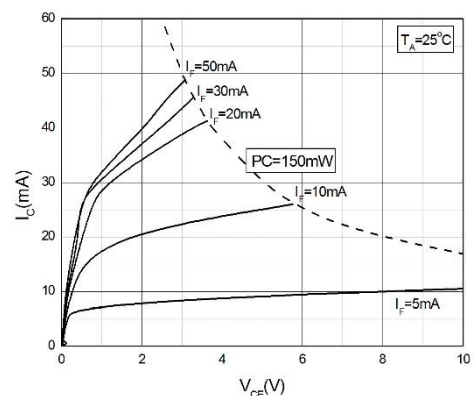
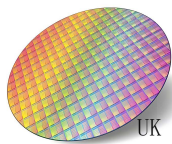


Fig.6 Collector Current vs. Collector-emitter Voltage





CHARACTERISTIC CURVES

Fig.7 Normalized Current Transfer Ratio vs. Forward Current

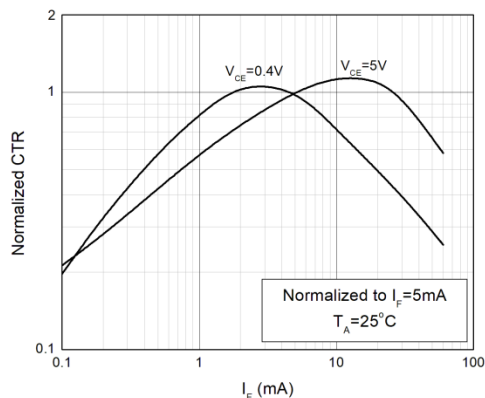


Fig.8 Normalized Current Transfer Ratio vs. Ambient Temperature

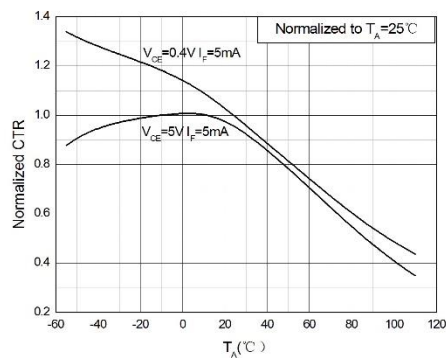


Fig.9 Collector-emitter Saturation Voltage vs. Ambient Temperature

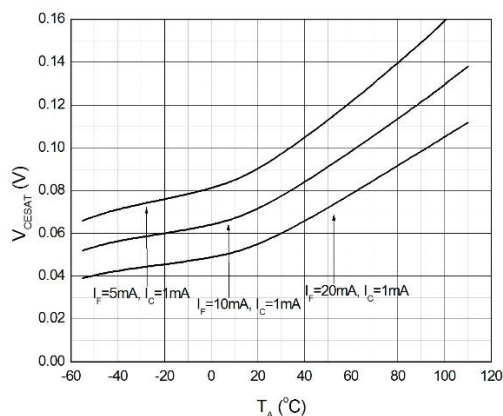


Fig.10 Switching Time vs. Load Resistance

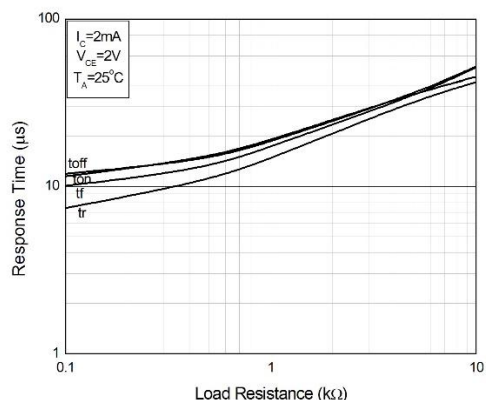
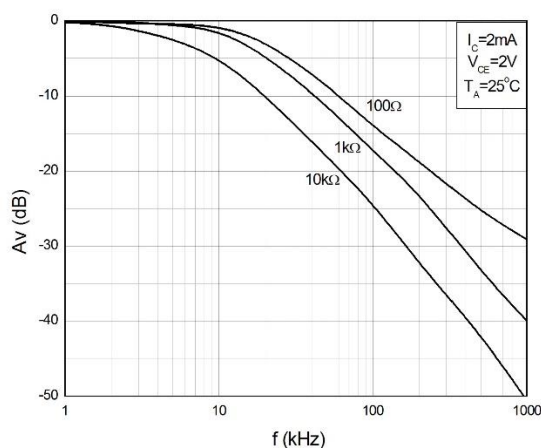
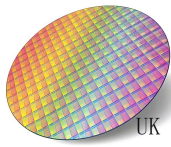


Fig.11 Frequency Response





TEST CIRCUITS

Fig.12 Test Circuits of Response Time

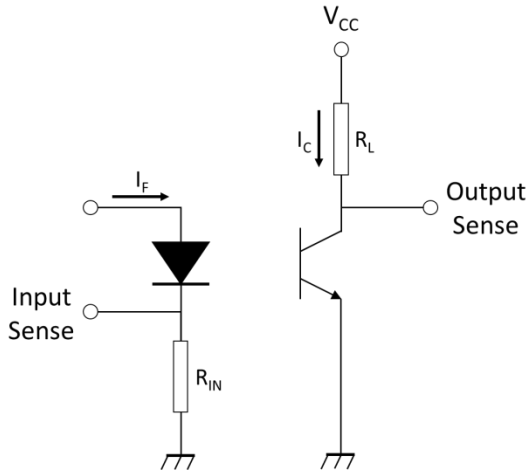


Fig.13 Curves of Response Time

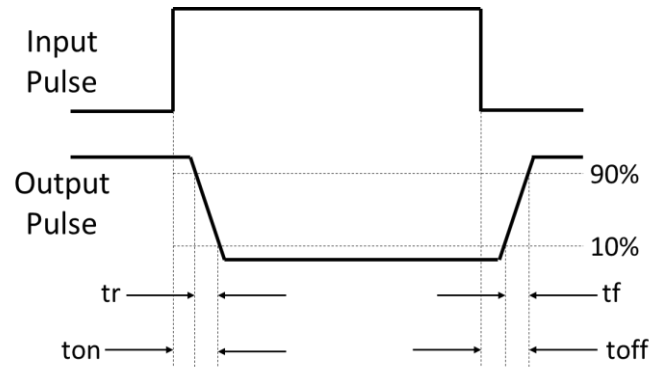
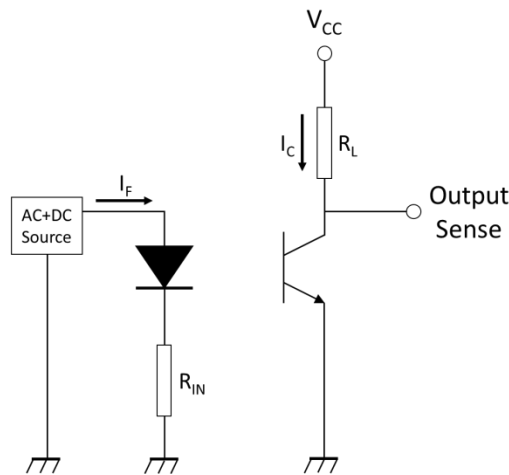
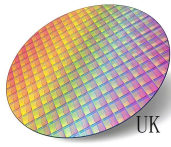
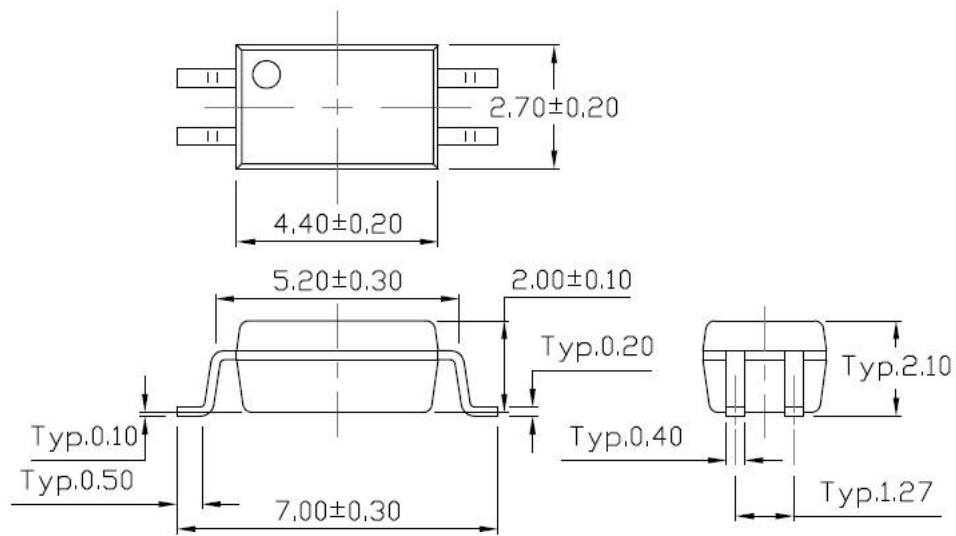


Fig.14 Test Circuits of Frequency Response

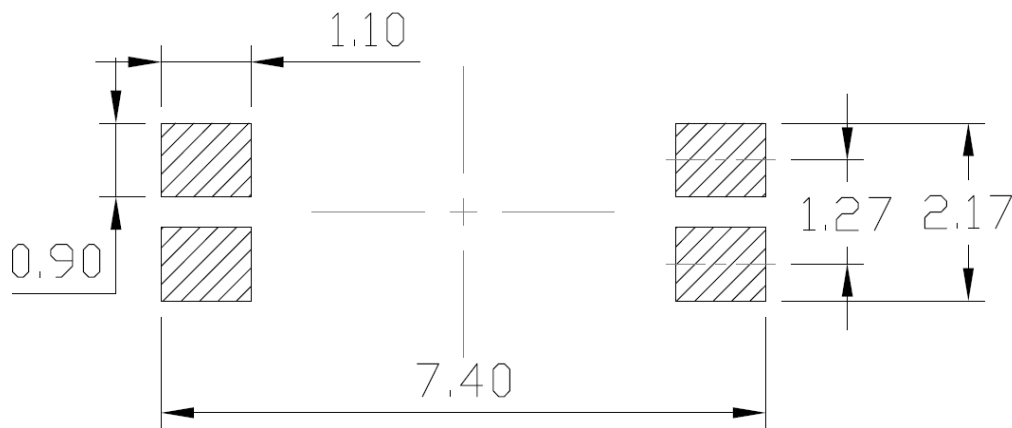




PACKAGE DIMENSIONS (Dimensions in mm unless otherwise stated)

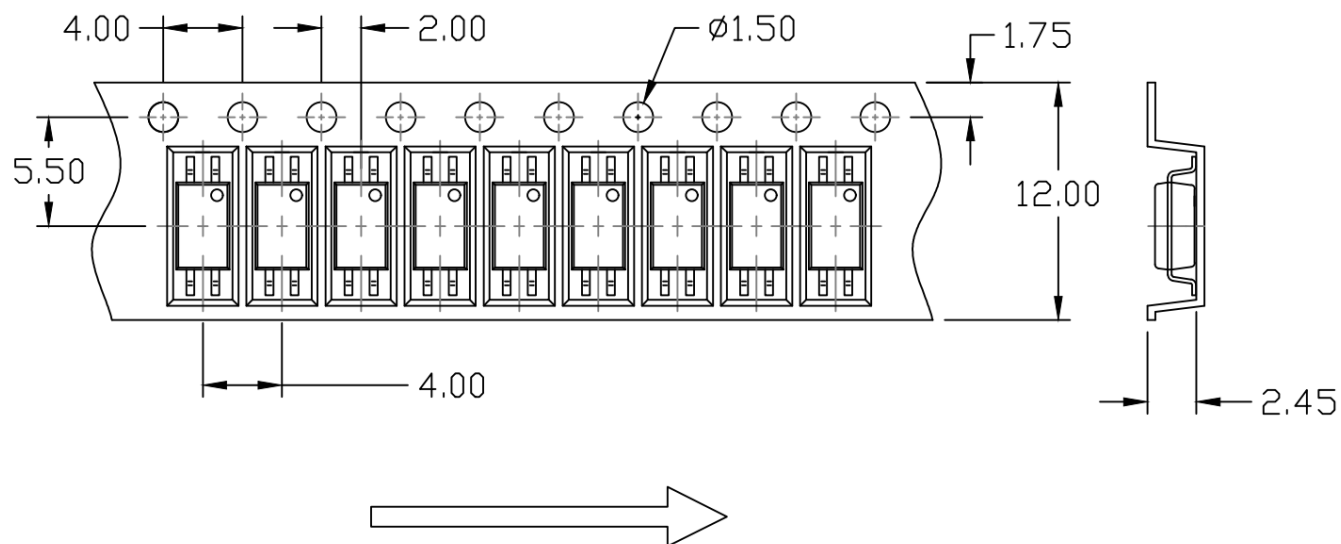


Recommended Solder Mask (Dimensions in mm unless otherwise stated)

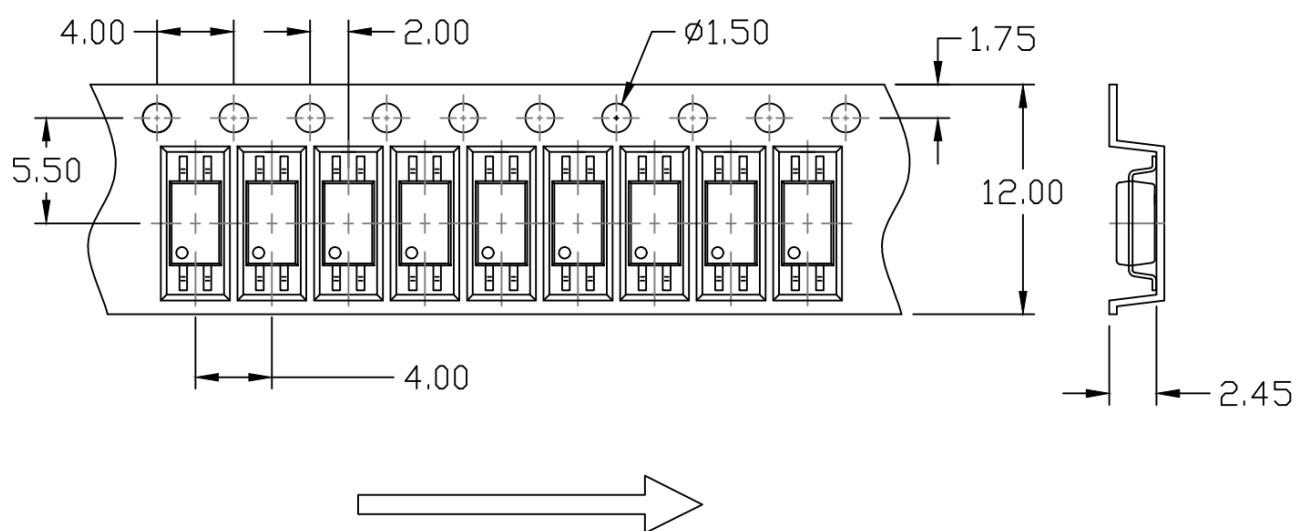


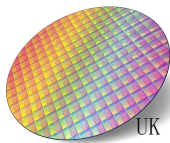
CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

Option T1



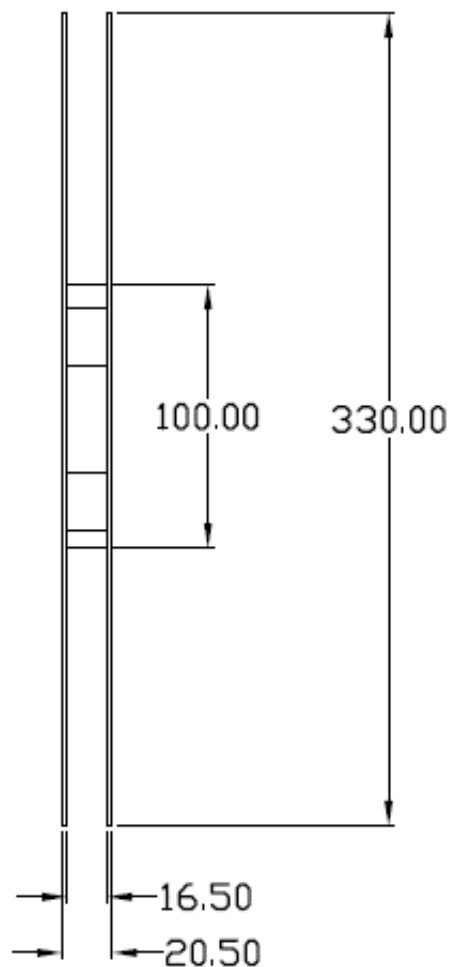
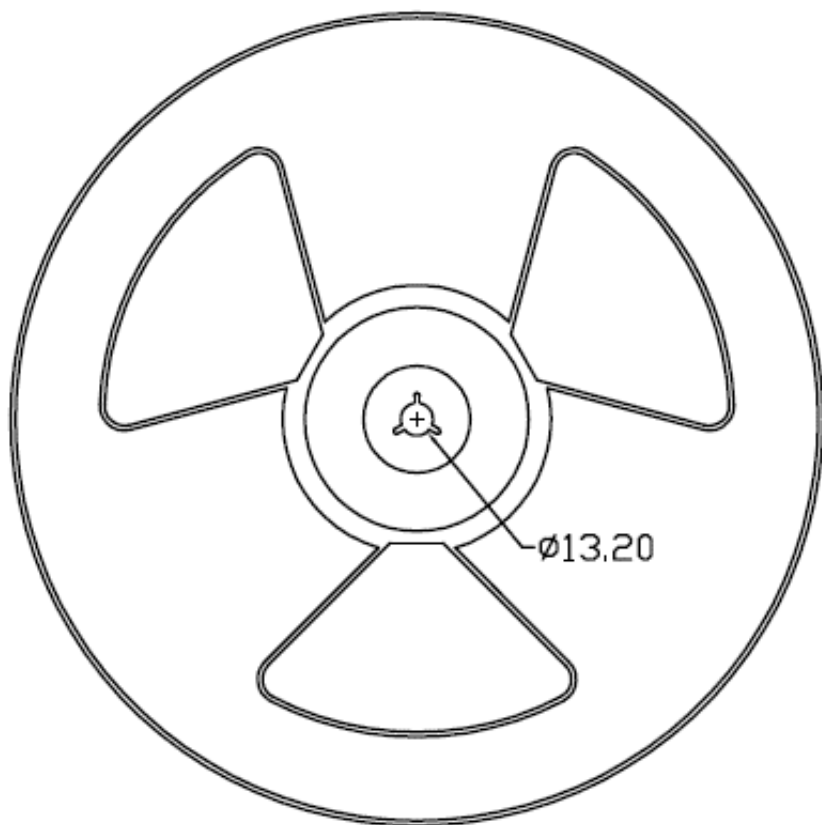
Option T2

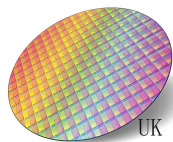




REEL SPECIFICATIONS (Dimensions in mm unless otherwise stated)

Option T1 & T2





ORDERING AND MARKING INFORMATION

MARKING INFORMATION



THP: Part Number

X : CTR grade, None/GB/GR/GRL/GRH

/ : denotes Company Abbr.

Y : denotes 1 digit Year code, Y=Year
(A-2010, B-2011, ... , K-2020, L-2021)

WW: denotes 2 digit Week code

ORDERING INFORMATION

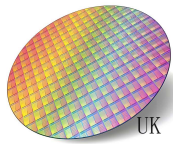
IS281x

IS281: Part Number

X: CTR grade, None/GB/GR/GRL/GRH

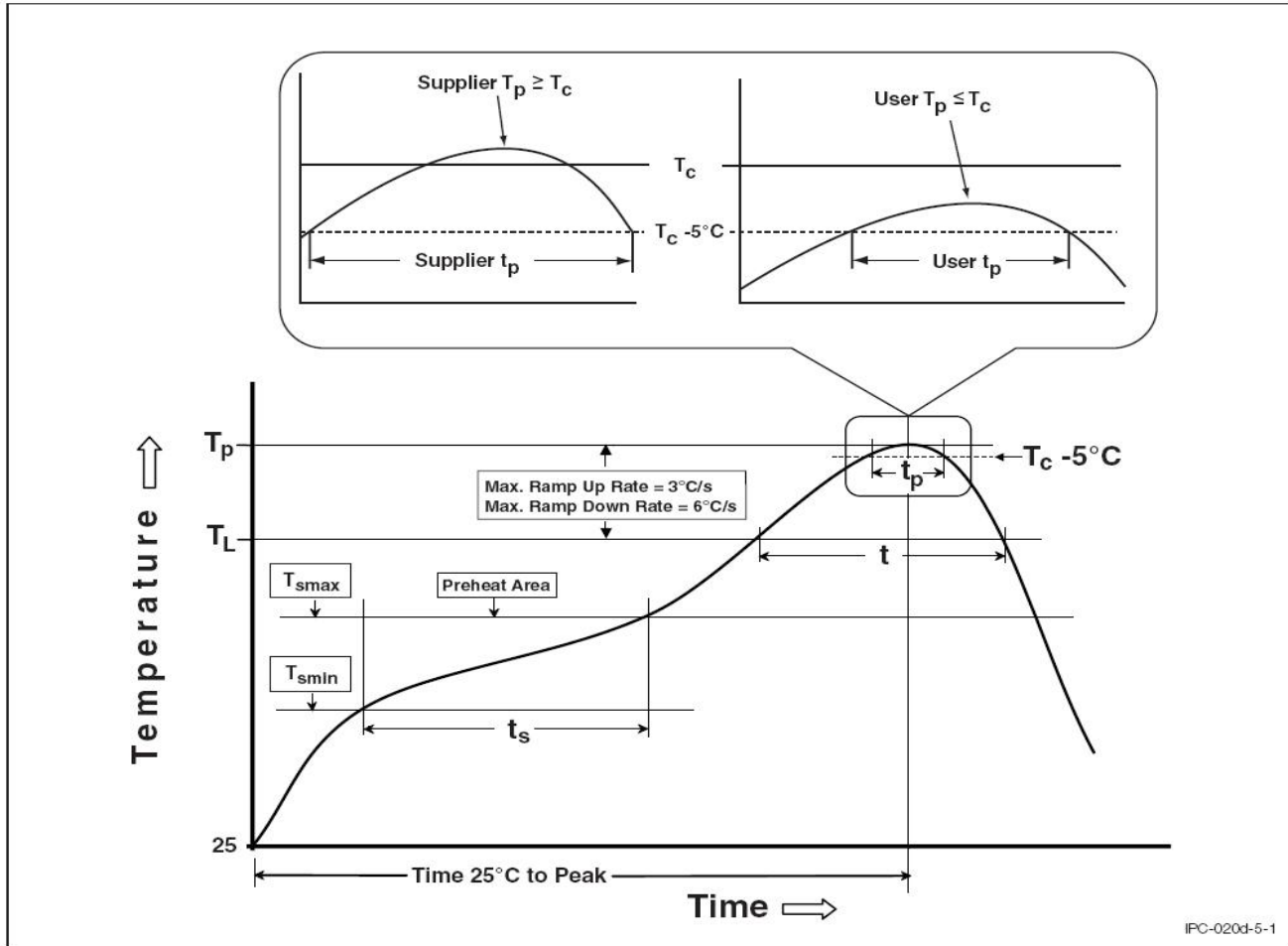
PACKING QUANTITY

Option	Quantity	Quantity – Inner box	Quantity – Outer box
T1	3000 Units/Reel	2 Reels/Inner box	5 Inner box/Outer box = 30k Units
T2	3000 Units/Reel	2 Reels/Inner box	5 Inner box/Outer box = 30k Units

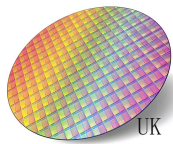


REFLOW INFORMATION

REFLOW PROFILE

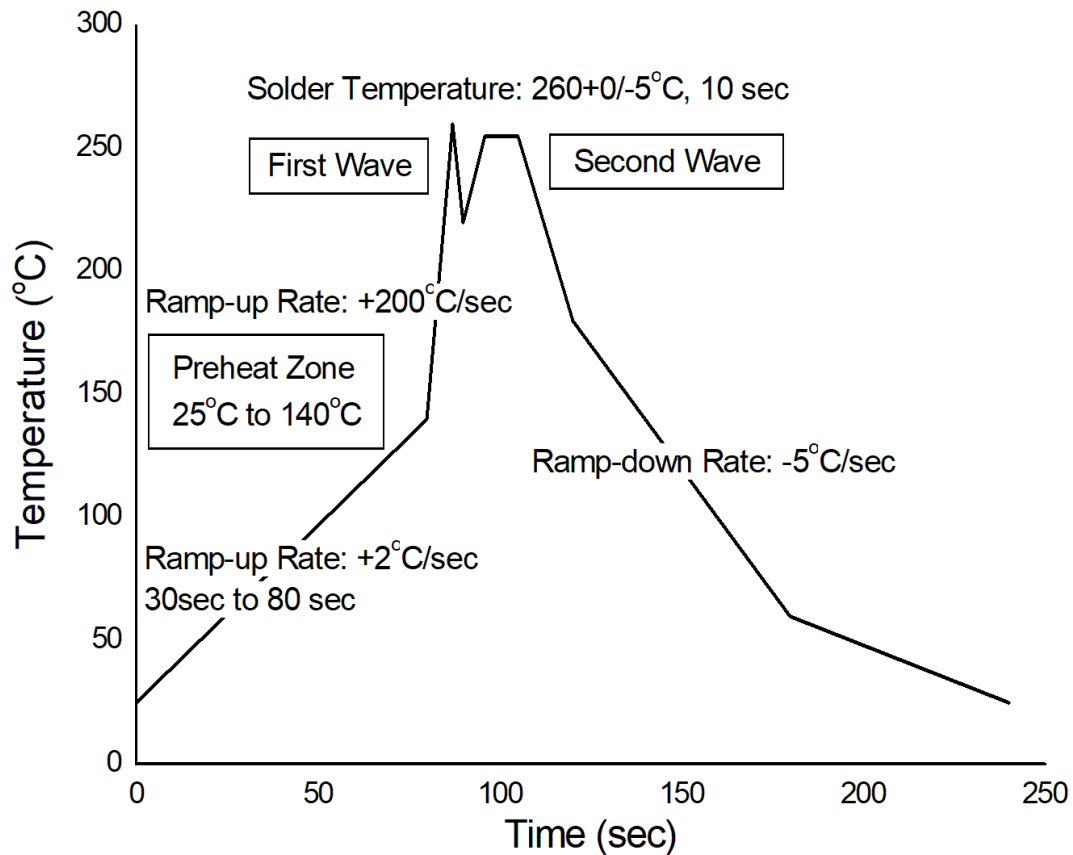


Profile Feature	Sn-Pb Assembly Profile	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	100	150°C
Temperature Max. (Tsmax)	150	200°C
Time (ts) from (Tsmin to Tsmax)	60-120 seconds	60-120 seconds
Ramp-up Rate (tL to tP)	3°C/second max.	3°C/second max.
Liquidous Temperature (TL)	183°C	217°C
Time (tL) Maintained Above (TL)	60 – 150 seconds	60 – 150 seconds
Peak Body Package Temperature	235°C +0°C / -5°C	260°C +0°C / -5°C
Time (tP) within 5°C of 260°C	20 seconds	30 seconds
Ramp-down Rate (TP to TL)	6°C/second max	6°C/second max
Time 25°C to Peak Temperature	6 minutes max.	8 minutes max.



TEMPERATURE PROFILE OF SOLDERING

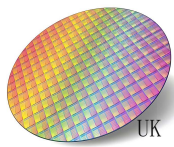
WAVE SOLDERING (JESD22-A111 COMPLIANT)



HAND SOLDERING BY SOLDERING IRON

Soldering Temperature	380+0/-5°C
Soldering Time	3 sec max.

- One time soldering is recommended for all soldering method.
- Do not solder more than three times for IR reflow soldering.



DISCLAIMER

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- The characteristic curves shown in this datasheet are representing typical performance which are not guaranteed.
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- Please contact ASG sales agent for special application request.
- Immerge unit's body in solder paste is not recommended.
- Parameters provided in datasheets may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated in each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify ASG's terms and conditions of purchase, including but not limited to the warranty expressed therein.
- Discoloration might be occurred on the package surface after soldering, reflow or long-time use. It neither impacts the performance nor reliability.